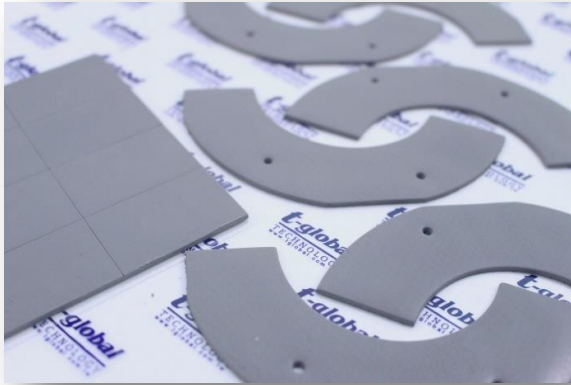


TGX

Ultra Soft Thermal Pad



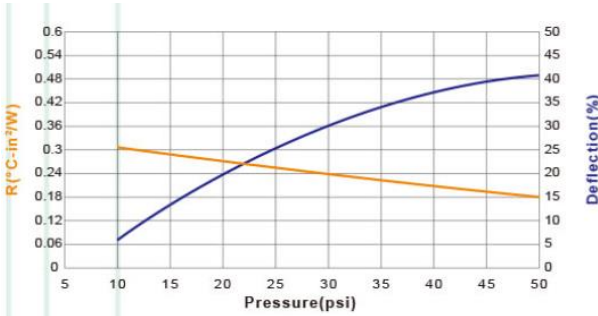
Features

- High-end product with thermal conductivity of 12 W / mK
- High compressibility
- Low hardness (Shore 00 65)
- Electrical insulation

Applications

- Usually used for industrial computers, military products
- Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub etc.

Thermal Resistance VS. Pressure VS. Deflection

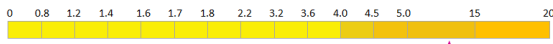


Pressure (psi)	R(°C - in ² /W)	Deflection(%)
10	0.31	6
30	0.24	30
50	0.18	41

Properties

- ◆ REACH Compliant
- ◆ RoHS Compliant
- ◆ UL Compliant

Thermal Conductivity: 12.0 W / mK



Hardness: 65 (Shore 00)

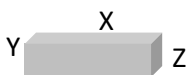


Testing sample thickness: 1.0mm

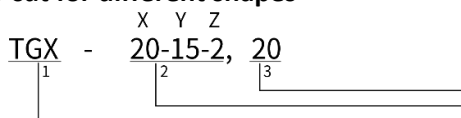
In "Thermal resistance V.S. Pressure V.S. Deflection" chart, TGX provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower, and deflection percentage gets higher. TGX provides good compliance and softness.

Properties	TGX	Unit	Tolerance	Test Method
Thermal Conductivity	12	W / mK	±1.2	ASTM D5470
Thickness	0.5~2.0	mm	-	ASTM D374
	0.0197~0.0787	inch	-	ASTM D374
Color	Gray	-	-	Visual
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	12	KV / mm	±1.2	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	3.4	g / cm ³	±0.2	ASTM D792
Working Temperature	-45~+200	°C	-	-
Volume Resistance	>10 ¹⁰	Ohm-m	-	ASTM D257
Standard Shape	-	Sheet ones	-	-
Hardness	65	Shore 00	±15	ASTM D2240

Need samples?



Pre-cut for different shapes



1. Choose the P/N
2. Fill into size: X, Y, Z
3. Fill the quantity you need

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Thermal Interface Materials: Thermal Pad, Thermal Tape, Thermal Grease, Ceramic Heat Spreader

